# DATA SHEET

74F779

8-bit bidirectional binary counter (3-State)

**Product specification** 

1989 Sep 20

IC15 Data Handbook







### 8-bit bidirectional binary counter (3-State)

74F779

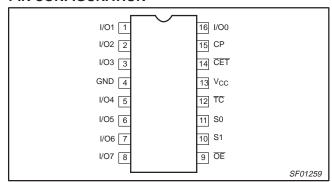
#### **FEATURES**

- Multiplexed 3-State I/O ports for bus oriented applications
- Built-in look-ahead carry capability
- Center power pins to reduce effects of package inductance
- Count frequency 145MHz typical
- Supply current 90mA typical
- See 74F269 for 24-pin separate I/O port version
- See 74F579 for 20-pin version
- See 74F1779 for extended function version of the 74F799

#### **DESCRIPTION**

The 74F779 is a fully synchronous 8-stage Up/Down Counter with multiplexed 3-State I/O ports for bus-oriented applications. All control functions (hold, count up, count down, synchronous load) are controlled by two mode pine (S0, S1). The device also features carry look-ahead for easy cascading. All state changes are initiated by the rising edge of the clock. When  $\overline{\text{CET}}$  is High the data outputs are held in their current state and  $\overline{\text{TC}}$  is held High. The  $\overline{\text{TC}}$  output is not recommended for use as a clock or asynchronous reset due to the possibility of decoding spikes.

#### **PIN CONFIGURATION**



TYPE	TYPICAL f <sub>MAX</sub>	TYPICAL SUPPLY CURRENT (TOTAL)
74F779	145MHz	90mA

#### ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE $V_{CC}$ = 5V $\pm 10\%$ , $T_{amb}$ = 0°C to +70°C	PKG DWG #		
16-Pin Plastic DIP	N74F779N	SOT38-4		
16-Pin Plastic SOL	N74F779D	SOT 162-1		

#### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
I/On	Data inputs	3.5/1.0	70μA/0.6mA
I/On	Data outputs	150/40	3.0mA/24mA
S0, S1	Select inputs	1.0/1.0	20μA/0.6mA
ŌĒ	Output Enable input (active Low)	1.0/1.0	20μA/0.6mA
CET	Count Enable Trickle input (active Low)	1.0/1.0	20μA/0.6mA
СР	Clock input (active rising edge)	1.0/1.0	20μA/0.6mA
TC	Terminal Count output (active Low)	50/33	1.0mA/20mA

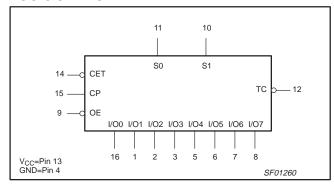
NOTE:

One (1.0) FAST Unit Load is defined as:  $20\mu A$  in the High state and 0.6mA in the Low state.

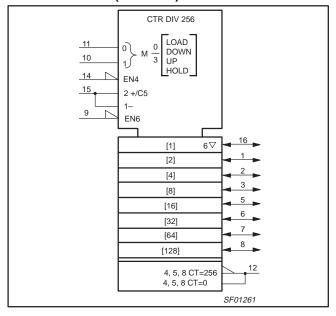
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#### **LOGIC SYMBOL**



#### LOGIC SYMBOL (IEEE/IEC)



#### **FUNCTION TABLE**

	ı	INPUTS	3		OPERATING MODE
S1	S0	CET	ΟE	СР	
ХХ		Х	Н	Х	I/O0 to I/O7 in High impedance
X X X L		L	Χ	Flip-flop outputs appear on I/O lines	
L	L	Х	Н	1	Parallel load all flip-flops
(not	LL)	Н	Χ	$\uparrow$	Hold (TC held High)
H L L X		1	Count up		
L	Н	L	Х	$\uparrow$	Count down

H = High voltage level
L = Low voltage level
X = Don't care

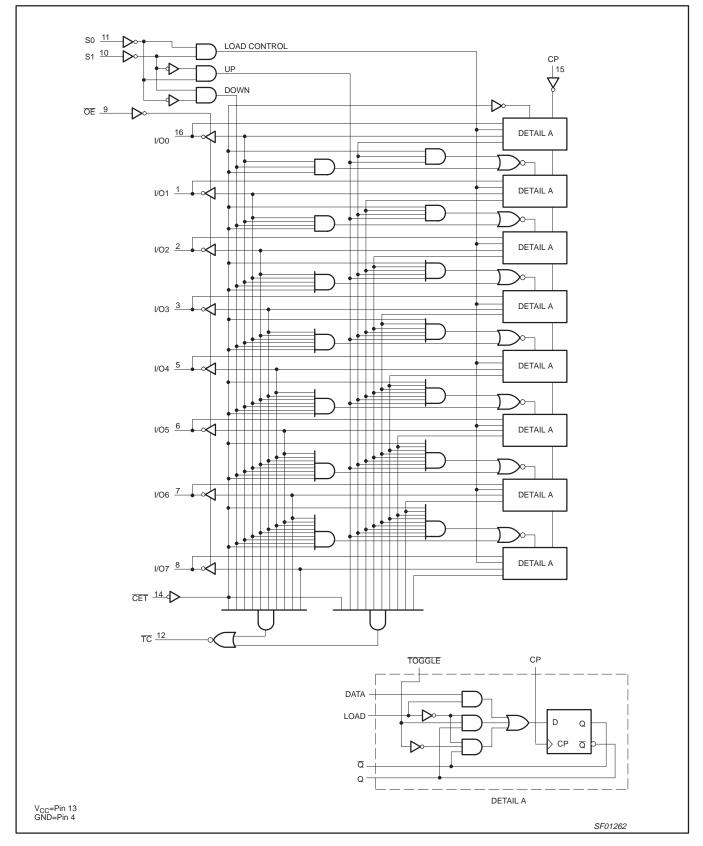
= Low-to-High clock transition

(not LL) = S0 and S1 should never be Low voltage level at the same time in the hold mode only.

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#### **LOGIC DIAGRAM**



### 8-bit bidirectional binary counter (3-State)

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#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT		
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V		
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V		
I <sub>IN</sub>	Input current		−30 to +5 m			
V <sub>OUT</sub>	Voltage applied to output in High output state	–0.5 to V <sub>CC</sub>	V			
Гоит		TC	40	mA		
	Current applied to output in Low output state	48	mA			
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C			
T <sub>stg</sub>	Storage temperature		-65 to +150	°C		

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMET	TED.			LIMITS		UNIT
STWIBUL	PARAME	EK	MIM	1	NOM	MAX	UNII
V <sub>CC</sub>	Supply voltage	pply voltage				5.5	V
V <sub>IH</sub>	High-level input voltage	2.0				V	
V <sub>IL</sub>	Low-level input voltage				0.8	V	
I <sub>IK</sub>	Input clamp current				-18	mA	
		TC				-1	mA
IOH	High-level output current	I/On				-3	mA
	l and land and and and	TC				20	mA
I <sub>OL</sub>	Low-level output current				24	mA	
T <sub>amb</sub>	Operating free-air temperature range	perating free-air temperature range				70	°C

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#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

						LIMITS			
SYMBOL	PARAMETER		TES	CONDITIONS	SNO TAG	MIN	TYP NO TAG	MAX	UNIT
		TC	$V_{CC} = MIN,$ $V_{II} = MAX$	Ι	±10%V <sub>CC</sub>	2.5			V
	LP at law at a standard and		$V_{IH} = MIN$	$I_{OH} = -1 \text{mA}$	±5%V <sub>CC</sub>	2.7	3.4		V
V <sub>OH</sub>	High-level output voltage	1/0	V <sub>CC</sub> = MIN,	I <sub>OH</sub> = -3mA	±10%V <sub>CC</sub>	2.4			V
		I/On	$V_{IL} = MAX$ $V_{IH} = MIN$		±5%V <sub>CC</sub>	2.7	3.3		V
	Level and a standard and		$V_{CC} = MIN,$	I MAN	±10%V <sub>CC</sub>		0.30	0.50	V
$V_{OL}$	Low-level output voltage	$V_{IL} = MAX$ $V_{IH} = MIN$	$I_{OL} = MAX$	±5%V <sub>CC</sub>		0.35	0.50	V	
V <sub>IK</sub>	Input clamp voltage		V <sub>CC</sub> = MIN, I	ı = I <sub>IK</sub>			-0.73	-1.2	V
I.	Input current at maximum	I/On	$V_{CC} = 5.5V, V_{CC} = 5.5V$			1	mA		
Ч	input voltage	others	$V_{CC} = 5.5V, V_{CC} = 5.5V$	$V_1 = 7.0V$				100	μΑ
I <sub>IH</sub>	High-level input current	except	$V_{CC} = MAX$ ,	V <sub>I</sub> = 2.7V				20	μΑ
I <sub>IL</sub>	Low-level input current	I/On	V <sub>CC</sub> = MAX,	$V_{CC} = MAX, V_I = 2.7V$ $V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
I <sub>IH</sub> +I <sub>OZH</sub>	Off-state output current High-level voltage applied	I/On	V <sub>CC</sub> = MAX,	V <sub>O</sub> = 2.7V				70	μΑ
I <sub>IL</sub> +I <sub>OZL</sub>	Off-state output current Low-level voltage applied	1/On	V <sub>CC</sub> = MAX,	V <sub>O</sub> = 0.5V				-600	μΑ
I <sub>OS</sub>	Short-circuit output current <sup>N</sup>	IO TAG	V <sub>CC</sub> = MAX		-60		-150	mA	
I <sub>CC</sub>		I <sub>CCH</sub>	V <sub>CC</sub> = MAX			82	116	mA	
	Supply current (total)	I <sub>CCL</sub>				91	128	mA	
		I <sub>CCZ</sub>	1				97	136	mA

#### **AC ELECTRICAL CHARACTERISTICS**

					LIMIT	·s		
SYMBOL	PARAMETER	TEST CONDITIONS	l '	<sub>lmb</sub> = +25° V <sub>CC</sub> = +5V 50pF, R <sub>L</sub> =	,	T <sub>amb</sub> = 0°C V <sub>CC</sub> = +5 C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
f <sub>MAX</sub>	Maximum clock frequency	Waveform 1	125	145		115		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to I/On	Waveform 1	4.5 5.5	7.0 8.0	10.5 10.5	4.5 5.5	11.0 11.0	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to TC	Waveform 1	4.5 4.5	7.0 7.0	9.0 9.0	4.5 4.5	10.0 10.0	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CET to TC	Waveform 2	3.0 3.0	4.5 5.5	6.5 7.5	2.5 2.5	7.5 8.0	ns ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable time to High or Low level	Waveform 4 Waveform 5	2.5 4.5	4.5 6.5	7.0 9.0	2.5 4.5	8.0 9.5	ns ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Enable time from High or Low level	Waveform 4 Waveform 5	1.0 1.0	3.0 4.0	6.5 7.0	1.0 1.0	8.0 8.0	ns ns

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
 Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, IOS tests should be performed last.

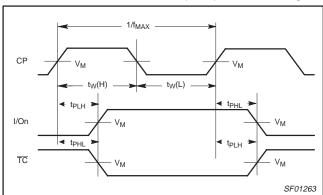
#### **AC SETUP REQUIREMENTS**

					LIMIT	s		
SYMBOL	PARAMETER	TEST CONDITIONS	T <sub>2</sub>	<sub>amb</sub> = +25° V <sub>CC</sub> = +5V 50pF, R <sub>L</sub> =	C 7 500Ω	$V_{CC} = +5$	UNIT	
			MIN	LIMITS $T_{amb} = +25^{\circ}C$ $V_{CC} = +5V$ $V_{CC} = +5V \pm 10\%$ $V_{CL} = 50pF, R_L = 500Ω$ TYP MAX MIN MAX $\begin{array}{c ccccccccccccccccccccccccccccccccccc$	MAX			
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time, High or Low I/O <sub>n</sub> to CP	Waveform 3	5.0 5.0					ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low I/O <sub>n</sub> to CP	Waveform 3	1.0 1.0					ns ns
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time, High or Low CET to CP	Waveform 3	5.0 5.5					ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low CET to CP	Waveform 3	0 0					ns ns
$t_{s}(H)$ $t_{s}(L)$	Setup time, High or Low Sn to CP	Waveform 3	8.0 8.0					ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low Sn to CP	Waveform 3	0 0					ns ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP Pulse width, High or Low	Waveform 1	4.0 4.0			4.0 4.0		ns ns

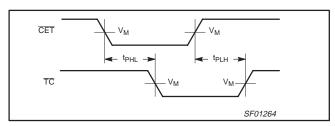
#### **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ .

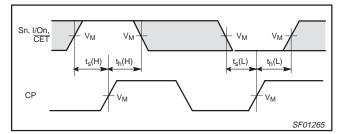
The shaded areas indicate when the input is permitted to change for predictable output performance.



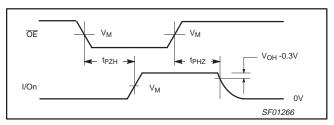
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



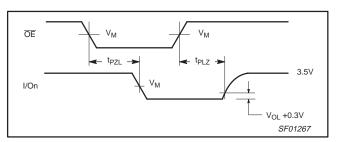
Waveform 2. Propagation Delay CET Input to Terminal Count Output



Waveform 3. Data Setup and Hold Times



Waveform 4. 3-State Output Enable Time to High Level and Output Disable Time from High Level

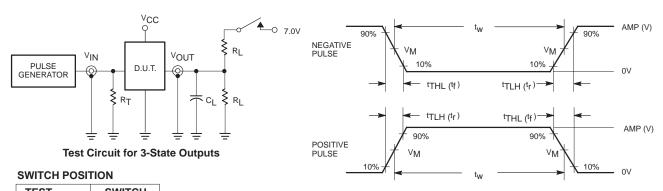


Waveform 5. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

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#### **TEST CIRCUIT AND WAVEFORMS**



TEST	SWITCH
t <sub>PLZ</sub>	closed
t <sub>PZL</sub>	closed
All other	open

#### **DEFINITIONS:**

R<sub>L</sub> = Load resistor;

see AC electrical characteristics for value.
Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.

Termination resistance should be equal to  $Z_{\mbox{\scriptsize OUT}}$  of  $R_T =$ pulse generators.

family	INP	INPUT PULSE REQUIREMENTS											
family	amplitude	$V_{\text{M}}$	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>							
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns							

**Input Pulse Definition** 

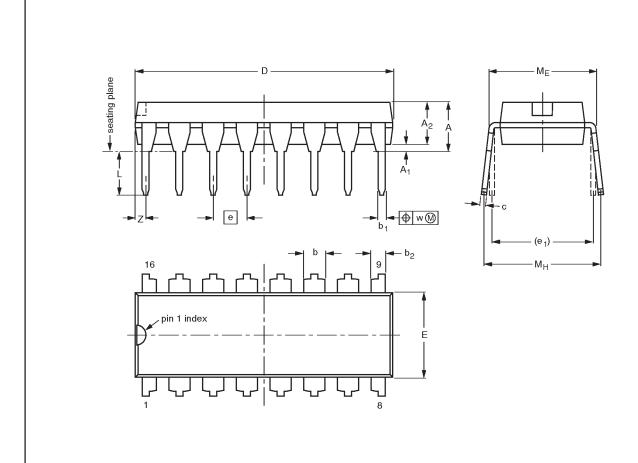
SF00777

### 8-bit bidirectional binary counter (3-State)

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DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	O	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	ME	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

10 mm

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

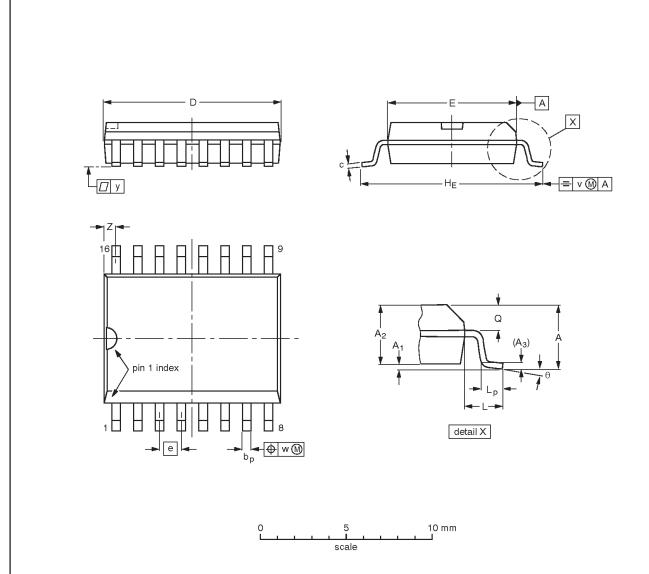
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT38-4						<del>92-11-17</del> 95-01-14

### 8-bit bidirectional binary counter (3-State)

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#### SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.419 0.394	0.055		0.043 0.039	0.01	0.01	0.004	0.035 0.016	O°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT162-1	075E03	MS-013AA			<del>95 01 24</del> 97-05-22

## 8-bit bidirectional binary counter (3-State)

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### **NOTES**

### 8-bit bidirectional binary counter (3-State)

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development.  Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date.  Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

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**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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